

## **Quarterly Reliability Monitoring Results**

## Quarters: Q3/2021 to Q4/2022

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number						
		PESD4USB5B-TTS						
		Part Description						
		NXP ICN8 Protection INDI MCD package						
								Test Conditions
			TEST					
	Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
# A1	PC Preconditioning	JESD22-A113 Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% Reflow soldering	24 hours 168 hours 3 cycles	211	12520	0		
# A1	Treconditioning	<u>-</u>	5 cycles	211	12320	U		
# B1	<b>HTRB</b> High Temperature Reverse Bias	MIL-STD-750-1 M1038 Method A Tj = Tjmax, Vr = 100% of max. datasheet reverse voltage	1000 hours	21	1280	0		
# A4	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000 cycles	78	4640	0		
# A3 <b>or</b>	<b>UHAST</b> Unbiased HAST	JESD22-A118 Tamb = 130 °C, RH = 85 %	— 96 hours	57	3420	0		
# A3 alt	<b>AC</b> Autoclave	JESD22-A102 Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)						
# A2 alt	<b>H3TRB</b> High Humidity High Temperature Reverse Bias	JESD22-A101 Tamb = 85 °C, RH = 85%, VR = 80 % of rated reverse voltage $^{[1]}$	1000 hours	75	4460	0		
# A5	<b>IOL</b> Intermittent Operating Life	MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta Tj$ = 100 °C for 15000 cycles	1000 hours	n.a.	n.a.	n.a.		
	RSH	JESD22-A111						
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	n.a.	n.a.	0		
# C10	<b>SD</b> Solderability	J-STD-002		111	1110	0		

<sup>[1]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
NXP ICN8	Protection INDI	1280	0	3,32	3,01E+08

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